

Year 2 Semester 1 updates: RD50-ENGRUN1 TCAD Simulations (Internal)

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Last few weeks:

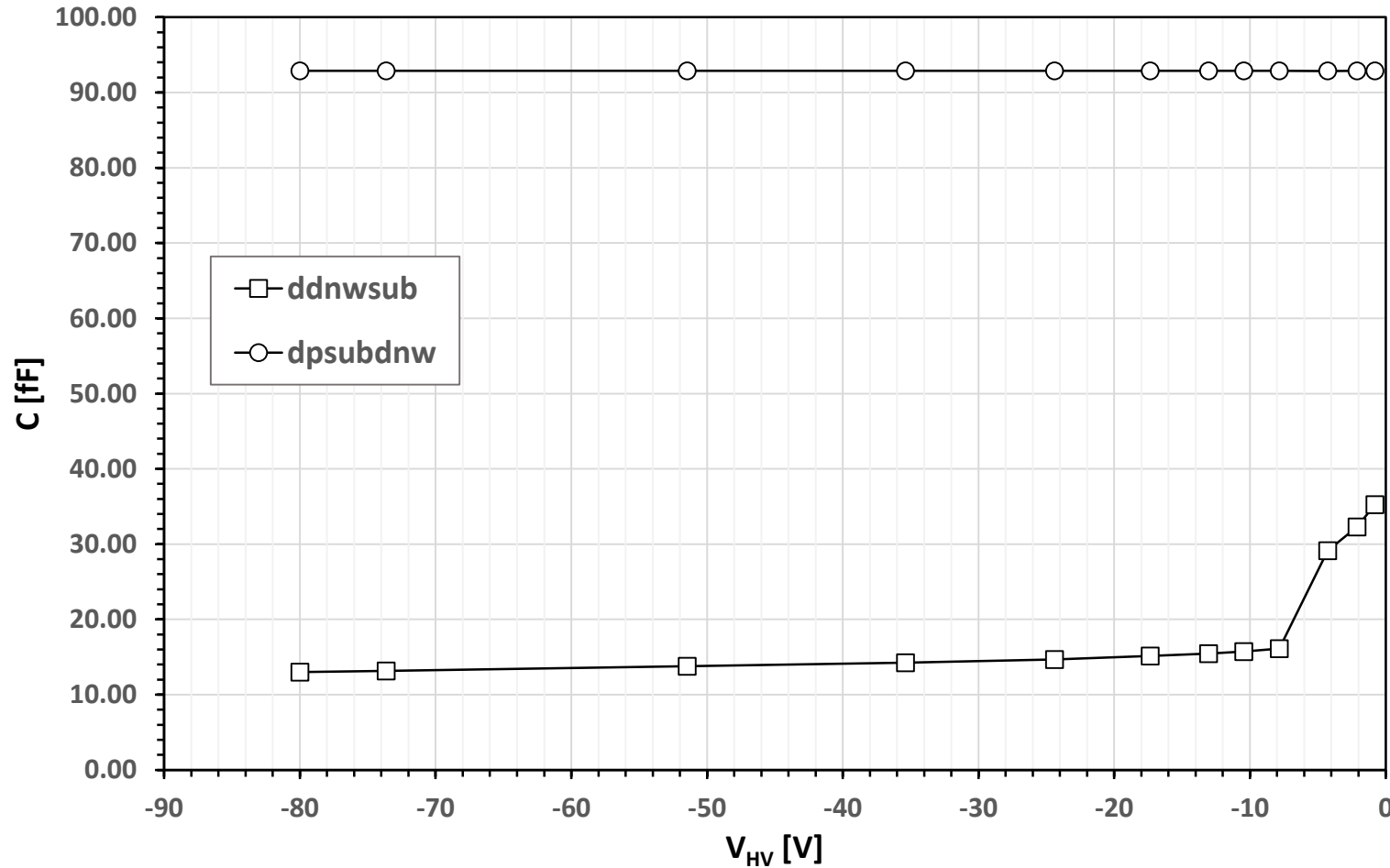
(Internal)

Using TCAD models of the RD50-MPW1 pixel to prepare for simulations of RD50-ENGRUN1 pixel (in matrix 5?)

- Parasitic Capacitance
 - Mixed-mode simulation with small AC analysis
 - Negative capacitances?
- Radiation Damage
 - Pennicard charge trapping
- Multiple pixels with spacing
 - Models dynamically created with spacing nz as input parameter

Parasitic capacitance simulations

(Internal)



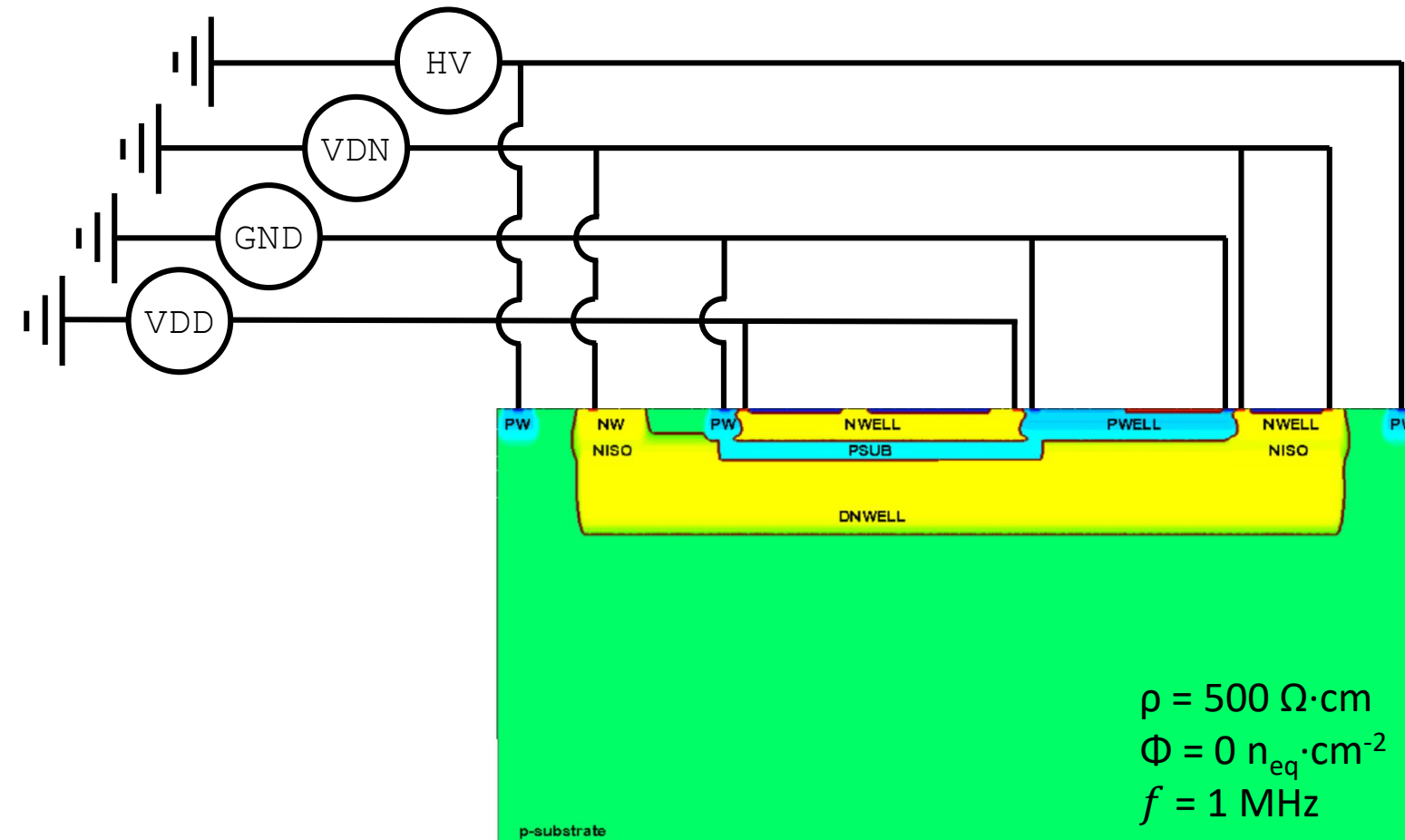
Using **RD50-MPW1** pixel simulations:

- Modelling parasitic capacitance
- (The capacitances come out negative!)
- C_{ddnwsub} too small $\rightarrow \approx 70$ fF @ -60V

dpsubdnw depth = 14.42 μm
ddnwsub depth = 42.5 μm

Mixed-mode simulation schematic

(Internal)



SPICE syntax:

```
Vsource_pset HV (n1 0) {dc = 0}  
Vsource_pset VDN (n2 0) {dc = 0}  
Vsource_pset VDD (n3 0) {dc = 0}  
Vsource_pset GND (n4 0) {dc = 0}
```

...

```
Goal {Parameter=VDD.dc Voltage=1.8}
```

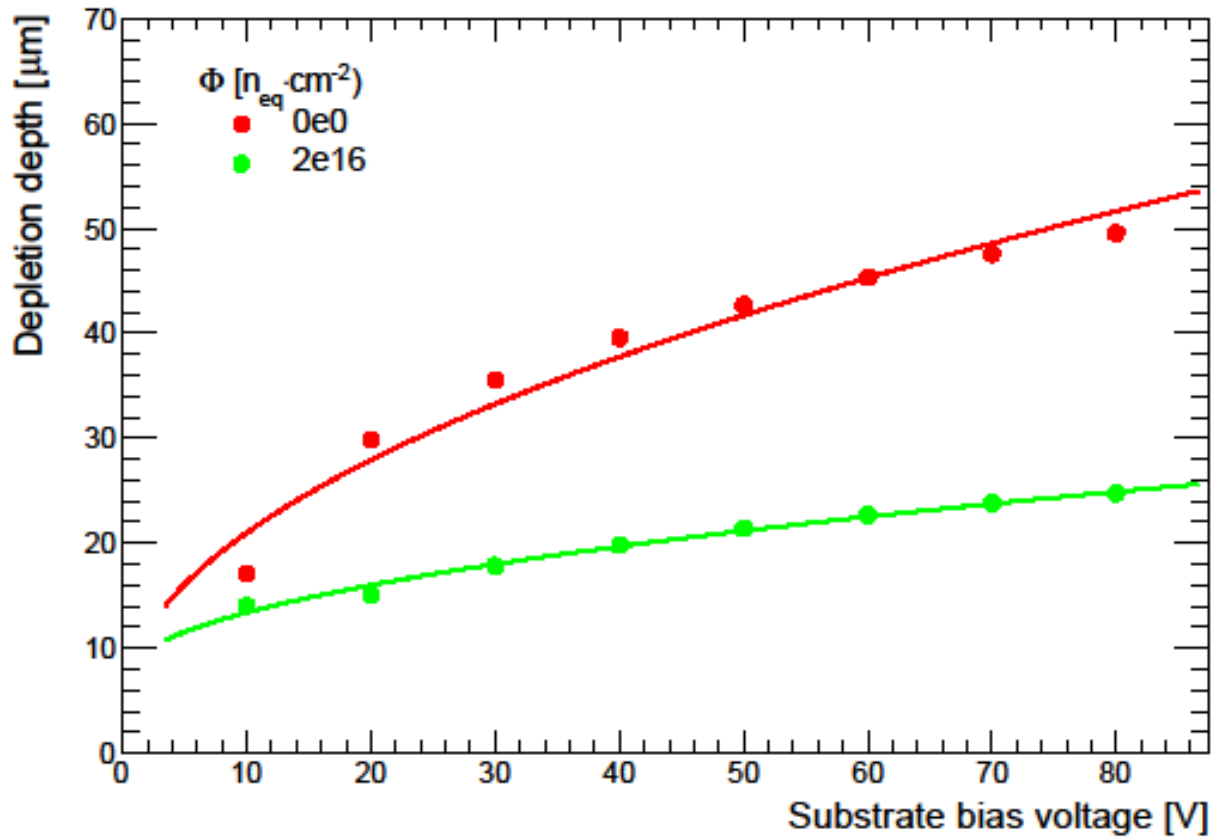
...

```
Goal {Parameter=VDN.dc Voltage=1.8}
```

...

```
Goal {Parameter=HV.dc Voltage=-80}
```

Radiation damage simulation and analysis (Internal)



Using **RD50-MPW1** pixel simulations:

- Modelling radiation damage using charge trapping (D. Pennicard)
- Initial simulation comparing “non-irradiated” pixel with one irradiated to $2\text{E}16 \text{ n}_{\text{eq}}\text{cm}^{-2}$

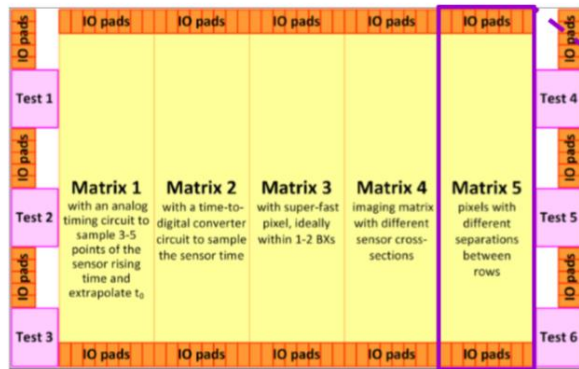
Type	Energy (eV)	Trap	σ_e (cm^2)	σ_h (cm^2)	η (cm^{-1})
Acceptor	$E_c - 0.42$	VV	$9.5 \cdot 10^{-15}$	$9.5 \cdot 10^{-14}$	1.613
Acceptor	$E_c - 0.46$	VVV	$5.0 \cdot 10^{-15}$	$5.0 \cdot 10^{-14}$	0.9
Donor	$E_c + 0.36$	CiOi	$3.23 \cdot 10^{-13}$	$3.23 \cdot 10^{-14}$	0.9

Table 1: D. Pennicard, UoGlasgow, PPT

Spacing between pixels

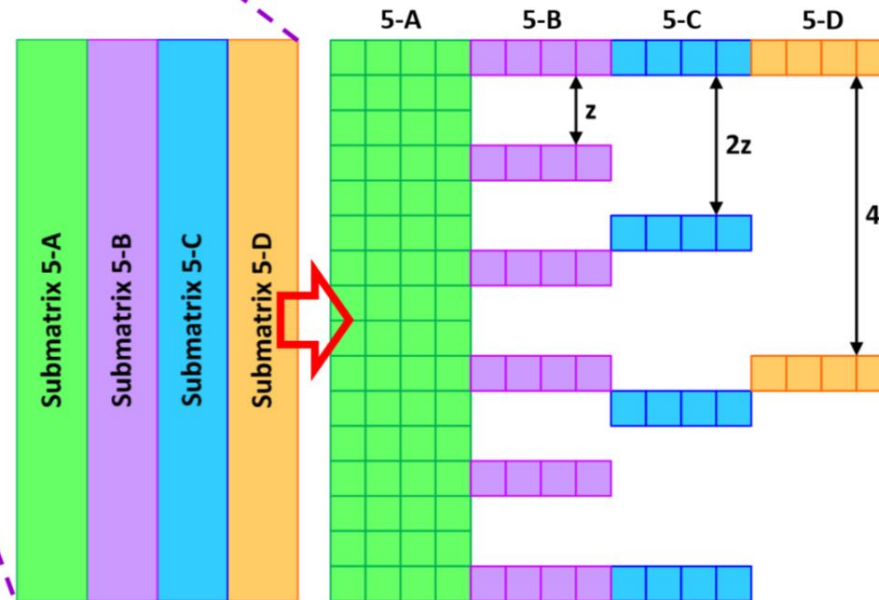
(Internal)

RD50-ENGRUN1 – Matrix 5 new approach



Matrix with different separations between rows

- Study the effects of dead areas between pixels on the charge collection efficiency of the sensor
- This matrix includes a few sub-matrices with different separations between rows of pixels
- The separations range between a few μm to some hundreds of μm
- Doing TCAD simulations at the moment



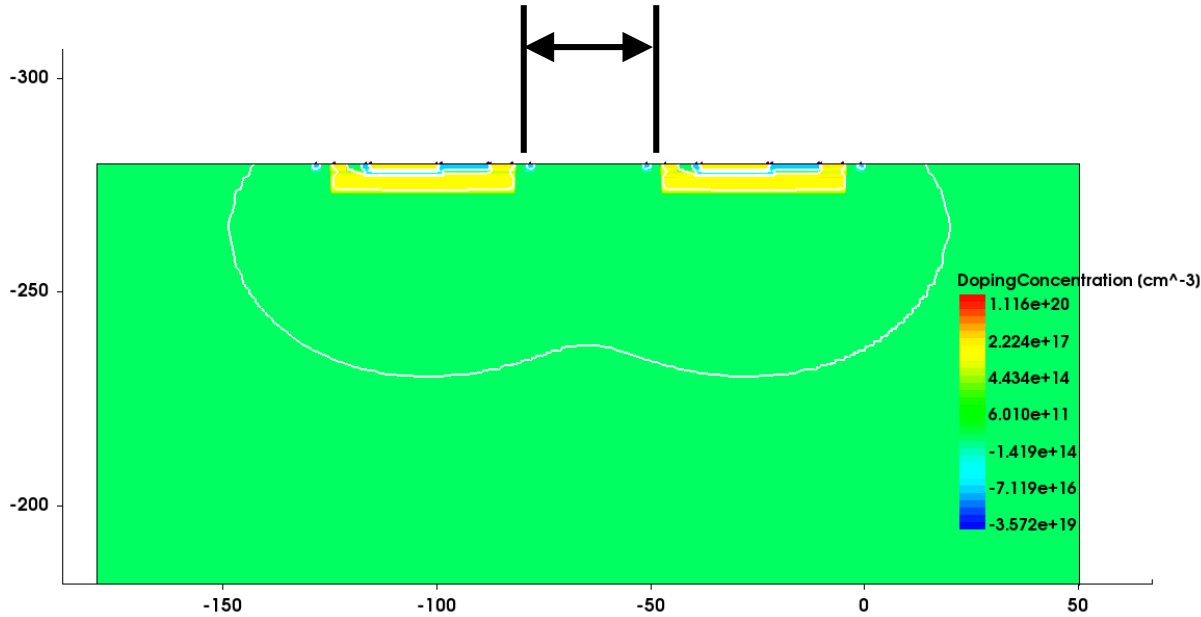
Using **RD50-MPW1** pixel simulations:

- $z = 25 \mu\text{m}$ (or whatever we choose... $\approx 50 \mu\text{m}$ on the diagram)
- Pixel models can be dynamically created for two pixels of spacing $1z$, $2z$, $4z$ etc.

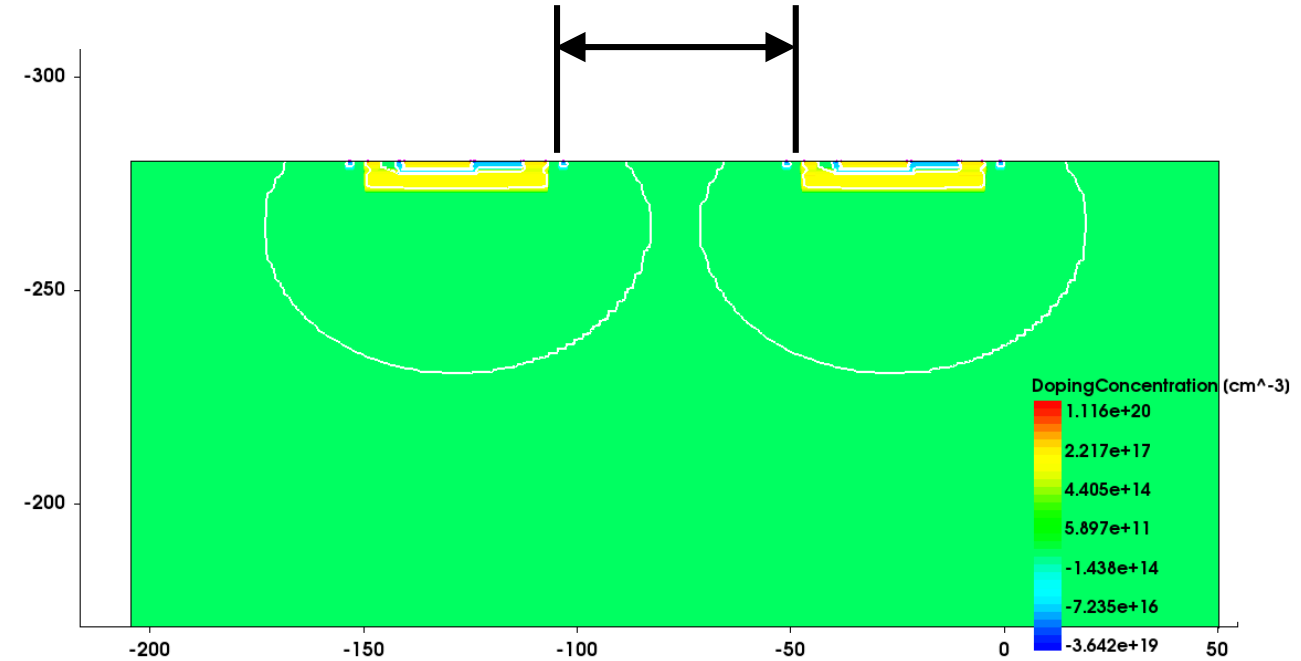
Spacing between pixels

(Internal)

$z = 25\mu\text{m}$



$2z = 50\mu\text{m}$



$$\begin{aligned} \rho &= 500 \Omega \cdot \text{cm} \\ \Phi &= 0 \text{ n}_{\text{eq}} \cdot \text{cm}^{-2} \\ V_{\text{sub}} &= -80\text{V} \end{aligned}$$



Next steps: (?)

(Internal)

- ENGRUN1 simulations
 - Remove topside contacts (backside biasing) →
 - Thinning? (thickness currently 280 μm)
 - Guard rings?
- Radiation Damage
 - More fluences (2E13, 2E14, 2E15 etc.)
 - How does irradiation affect depletion region merging between two pixels?
- Multiple pixels with spacing
 - Radiation damage (previous point)
 - Higher z
 - Same simulations for 1.9 $\text{k}\Omega\cdot\text{cm}$ → increased depletion region size

